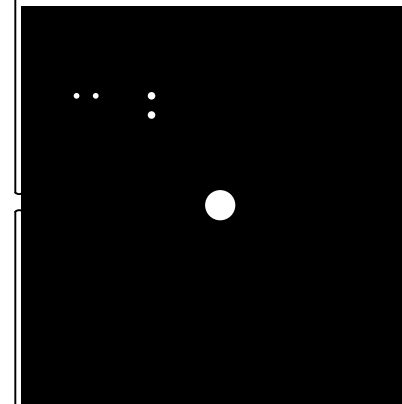
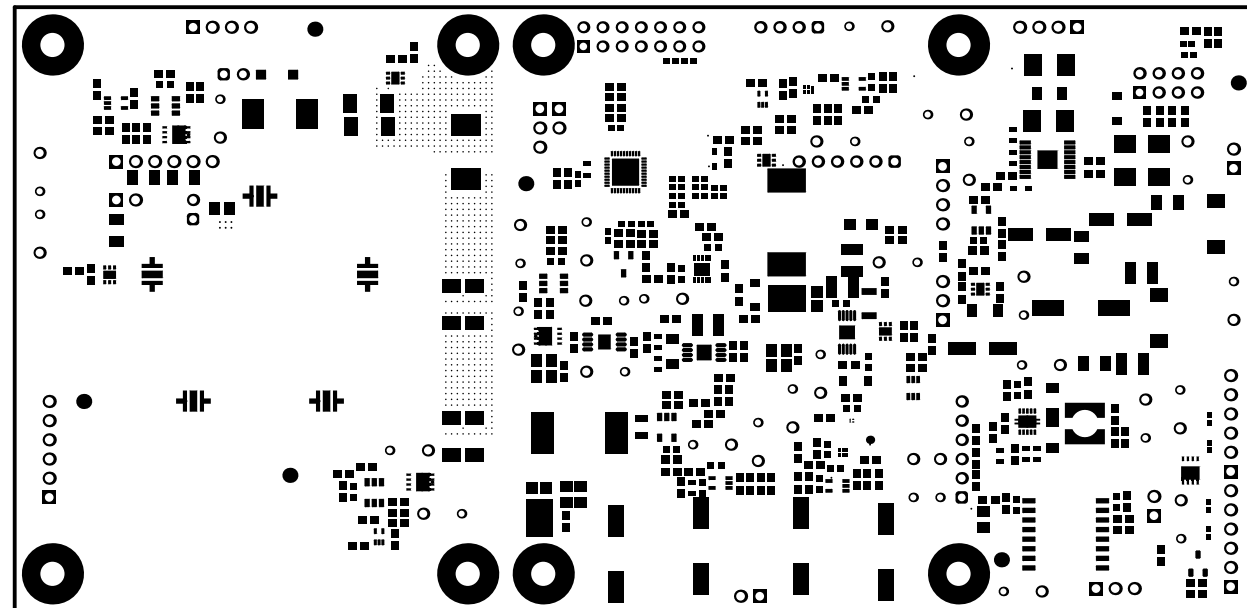
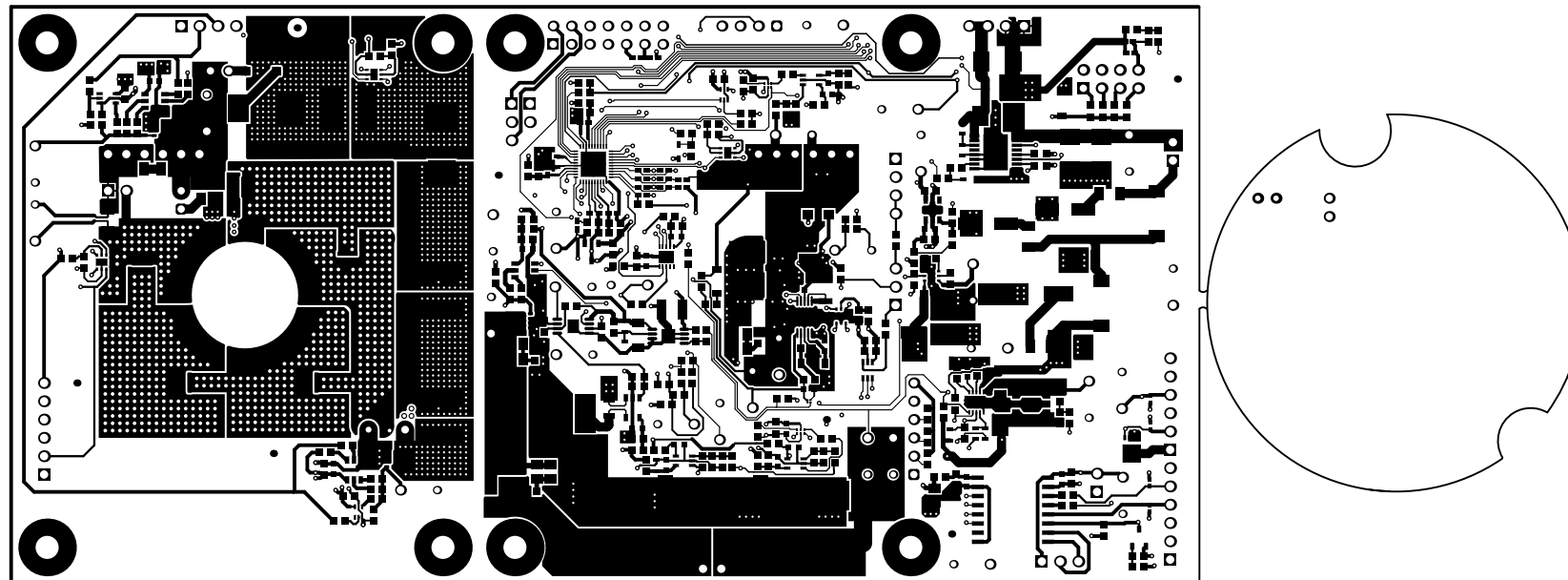


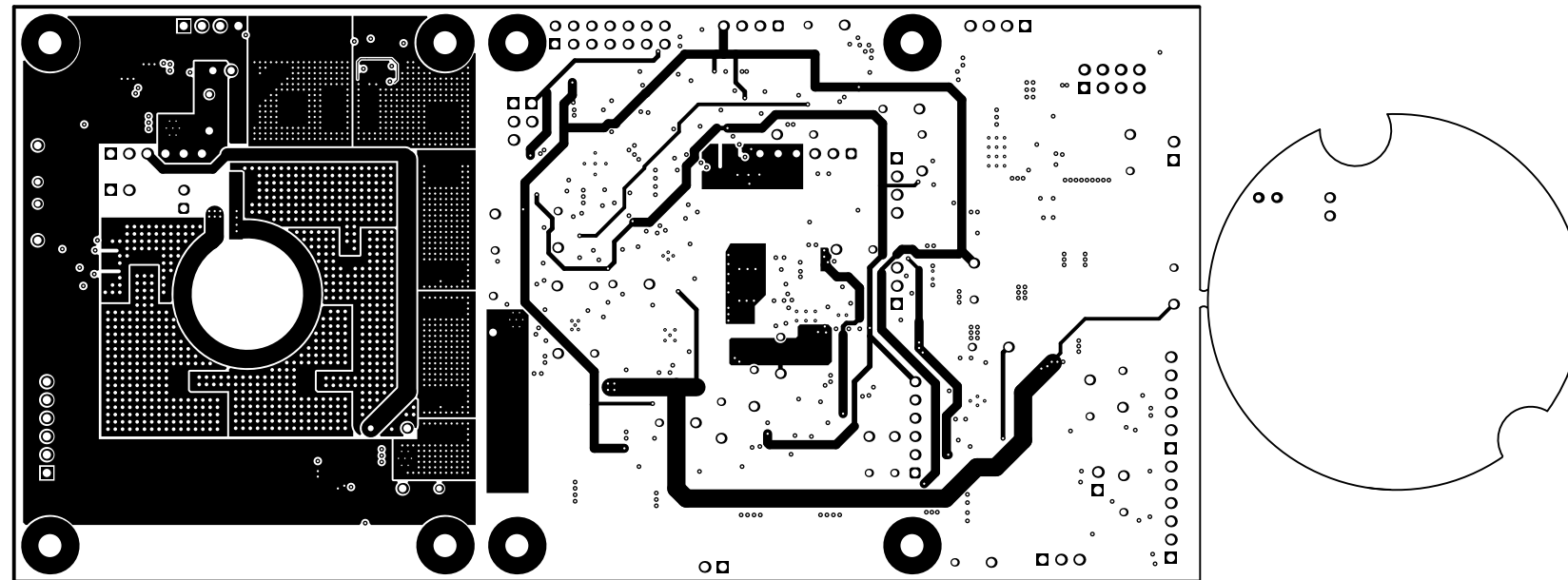
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01081		
PLOT NAME = Top Overlay	GENERATED : 12/12/2017 1:35:43 PM	TEXAS INSTRUMENTS	



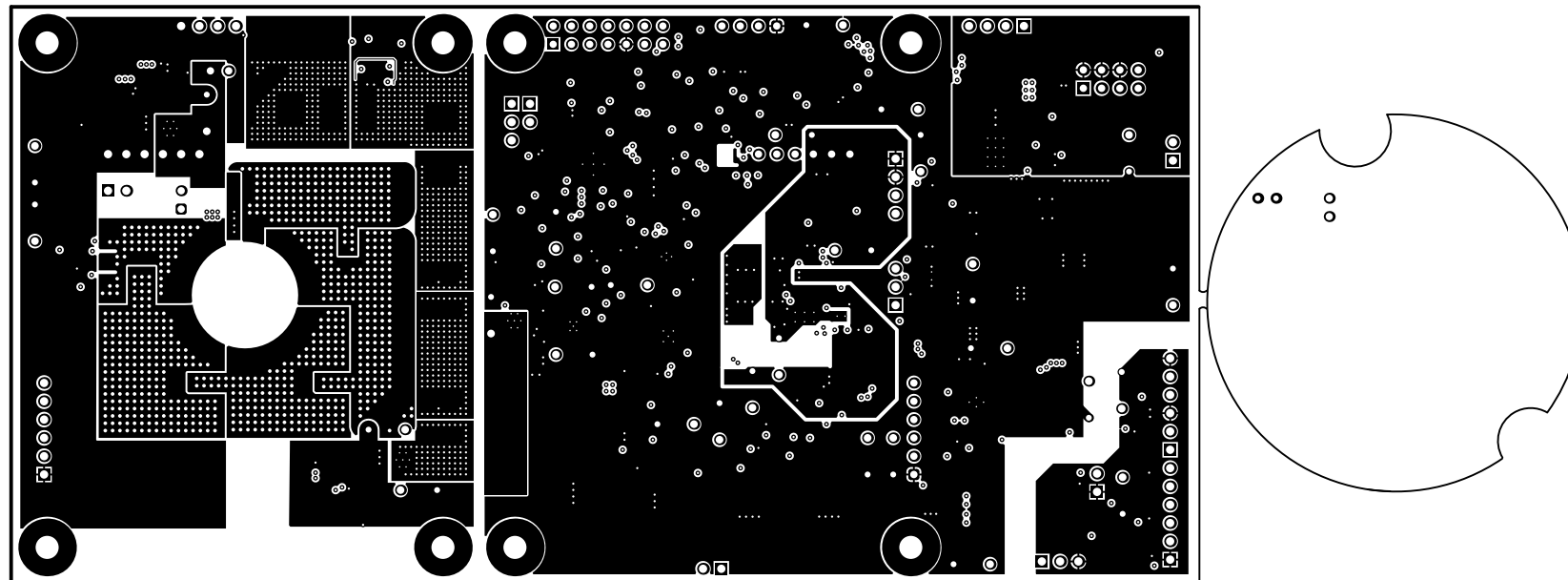
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01081		
PLOT NAME = Top Solder Mask	GENERATED : 12/12/2017 1:35:45 PM	TEXAS INSTRUMENTS	



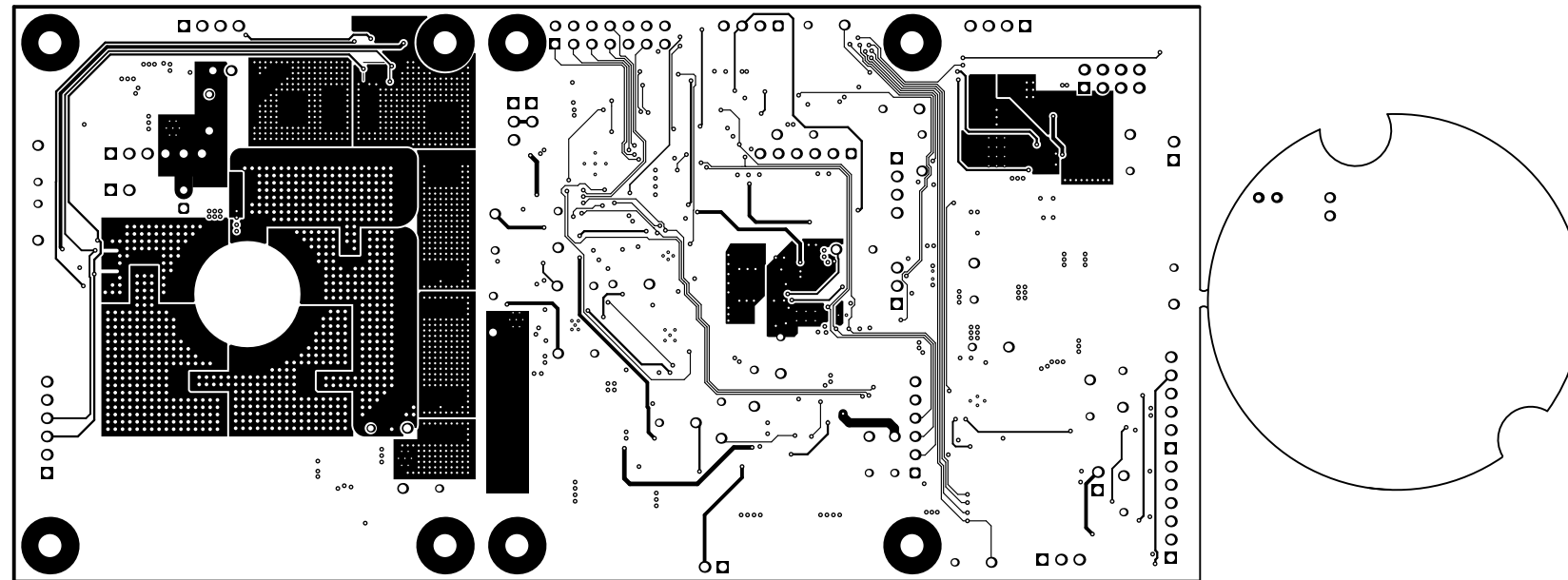
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01081		
PLOT NAME = Top Layer	GENERATED : 12/12/2017 1:35:46 PM	TEXAS INSTRUMENTS	



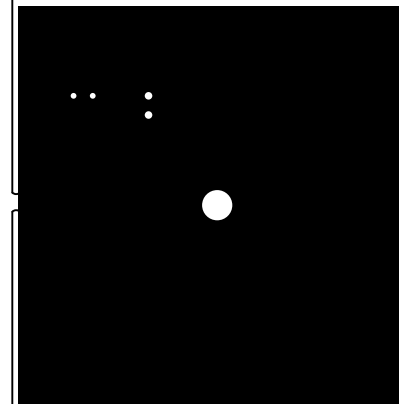
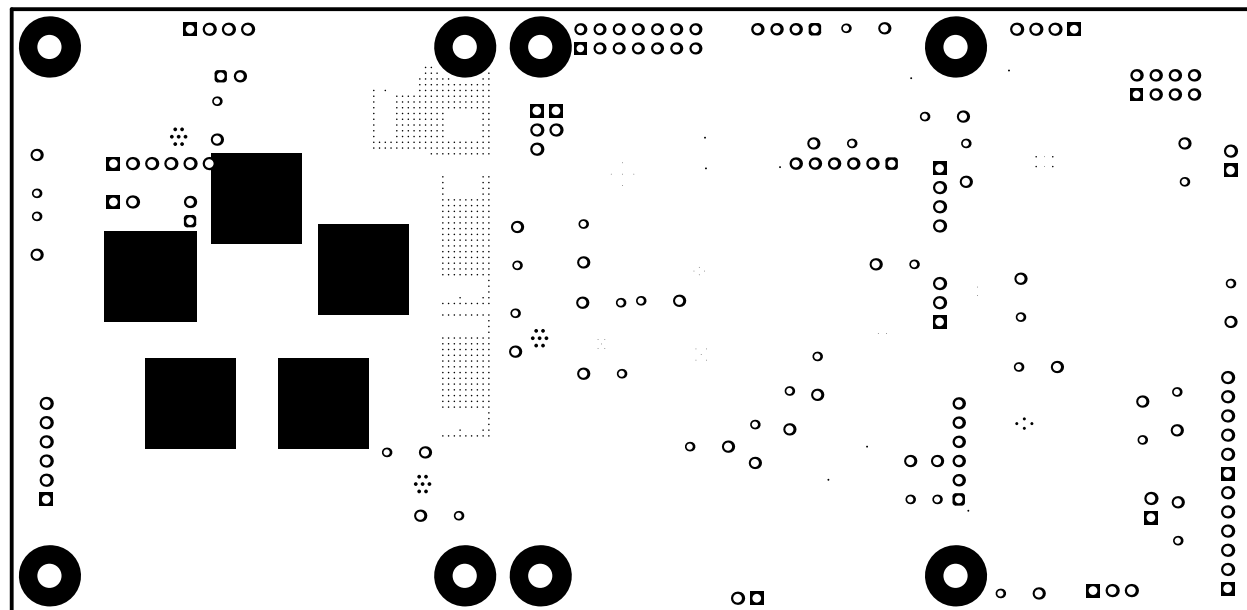
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = UCC	TID #: TIDA-01081		
PLOT NAME = Signal Layer 1	GENERATED : 12/12/2017 1:35:48 PM	TEXAS INSTRUMENTS	



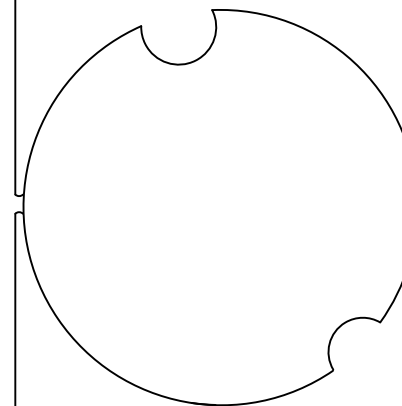
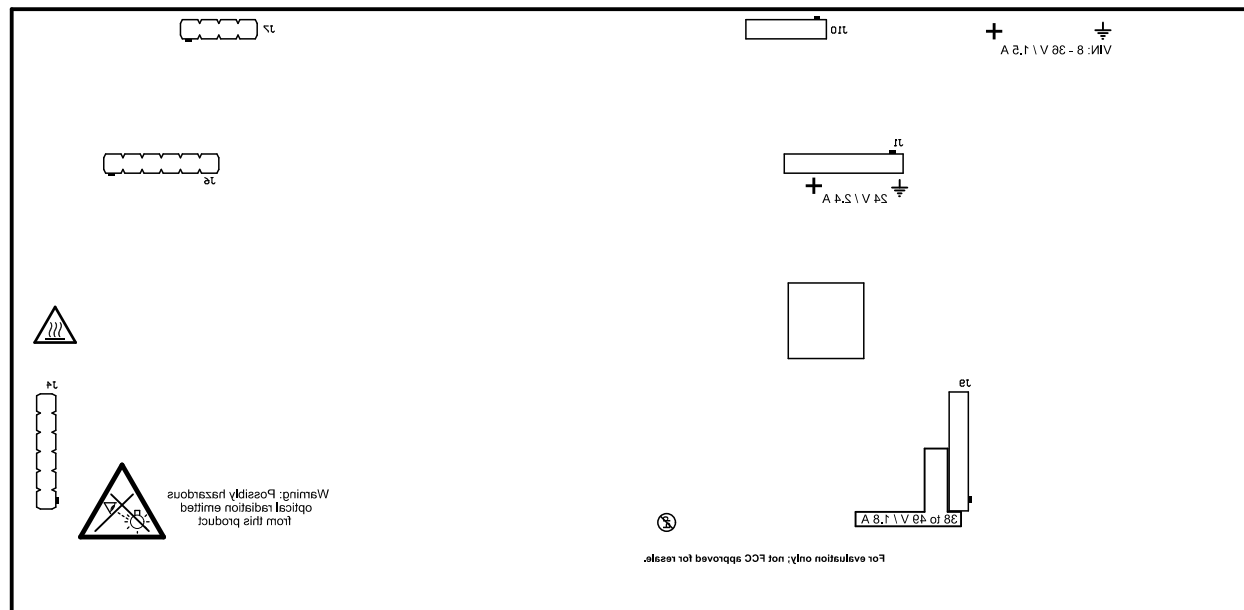
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: TIDA-01081		
PLOT NAME = Signal Layer 2	GENERATED : 12/12/2017 1:35:49 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01081		
PLOT NAME = Bottom Layer	GENERATED : 12/12/2017 1:35:50 PM	TEXAS INSTRUMENTS	

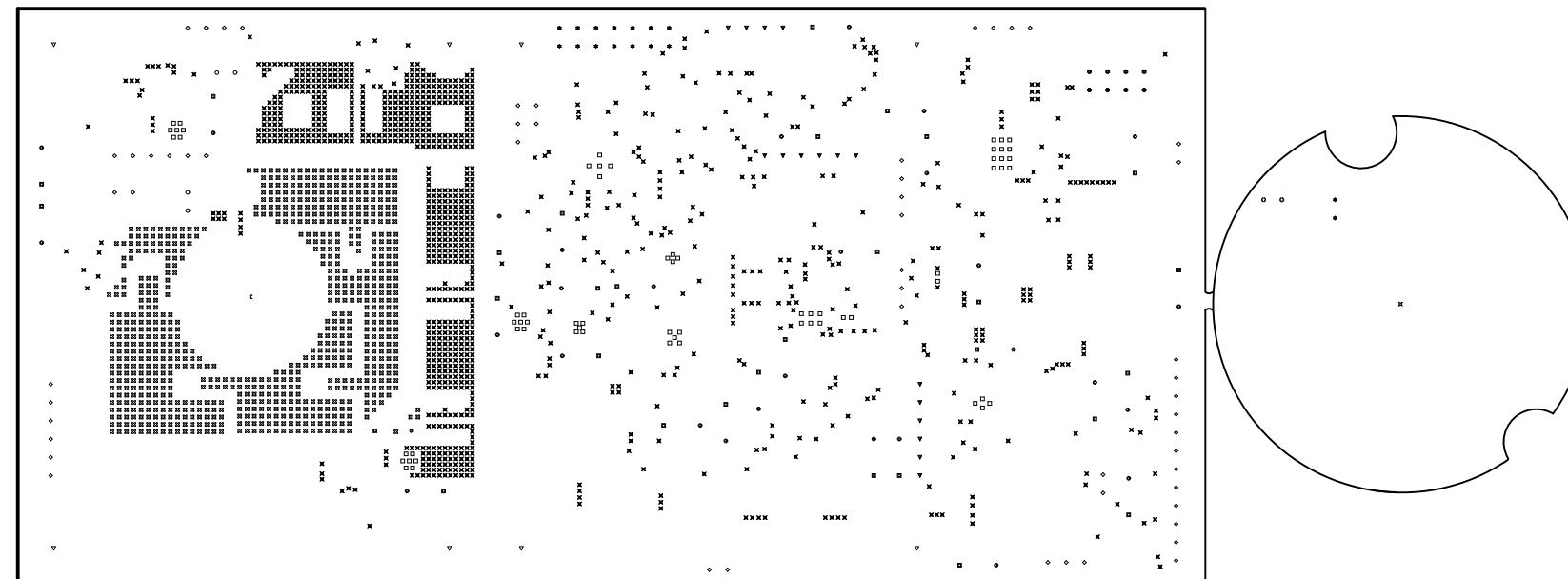


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01081		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/12/2017 1:35:52 PM	TEXAS INSTRUMENTS	

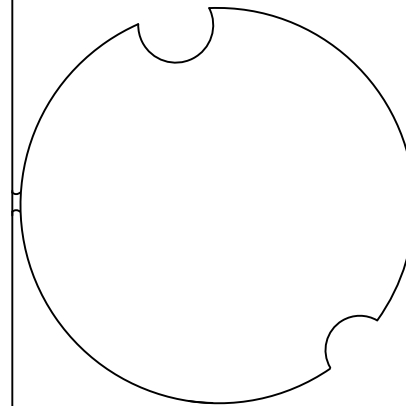
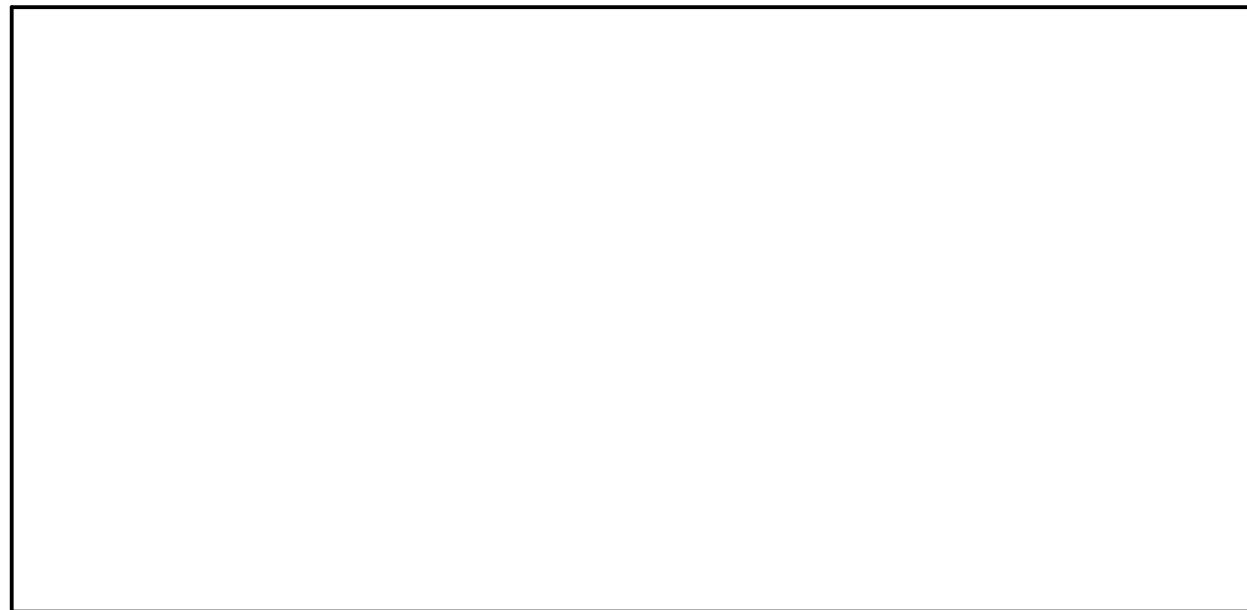


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01081		
PLOT NAME = Bottom Overlay	GENERATED : 12/12/2017 1:35:53 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
C	1	125.98mil (3.200mm)		Round	Top Layer - Bottom Layer	
X	1	157.48mil (4.000mm)	NPTH	Round	Top Layer - Bottom Layer	
□	66	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
X	1142	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
X	779	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	30	32.00mil (0.813mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	16	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	8	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	16	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	+/-1.97mil
○	4	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
○	30	42.00mil (1.067mm)	PTH	Round	Top Layer - Bottom Layer	
◇	55	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
▽	8	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	2158 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01081		
PLOT NAME = Drill Drawing	GENERATED : 12/12/2017 1:35:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01081	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01081		
PLOT NAME = Board Dimensions	GENERATED : 12/12/2017 1:36:01 PM		TEXAS INSTRUMENTS

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